

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	766	(702/58,59,81).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/07 17:14
L2	654	(702/82-84).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/07 17:17
L3	1028	(702/117,118).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/07 17:38
L4	975	(702/121,179,181).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/07 17:46
L5	670	(700/109-111).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/07 17:47
L6	716	(324/500).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/12/07 17:47
L7	1073	(702/182).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/12/07 17:49
L8	250	L7 and (semiconductor wafer (integrated adj circuit))	US-PGPUB; USPAT	OR	ON	2005/12/07 17:49
L9	212	702/183.ccls. and (semiconductor wafer (integrated adj circuit))	US-PGPUB; USPAT	OR	ON	2005/12/07 18:01
L10	1085	(324/537).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/12/07 18:04
L11	565	L10 and (semiconductor wafer (integrated adj circuit))	US-PGPUB; USPAT	OR	ON	2005/12/07 18:04
L12	4417	(324/765).CCLS.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/12/07 18:07
L13	212	L12 and (semiconductor wafer (integrated adj circuit)) and map	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/12/07 18:07
L14	1994	(438/14).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/12/07 18:09
L15	225	L14 and map	US-PGPUB; USPAT	OR	ON	2005/12/07 18:09
L16	1003	(438/17).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/12/07 18:18
L17	88	L16 and map	US-PGPUB; USPAT	OR	ON	2005/12/07 18:18
L18	2856	(438/17).CCLS.	EPO; JPO	OR	OFF	2005/12/07 18:19
L19	28	L18 and map	EPO; JPO	OR	ON	2005/12/07 18:19
L20	1397	(700/121).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/12/07 18:20

L21	201	L20 and map	US-PGPUB; USPAT	OR	ON	2005/12/07 18:20
L22	3	pass/fail adj map and @pd>"20050726"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/12/07 18:23
L23	0	((fail adj bit adj map) (wafer adj map) (wafer adj defect adj map)) and classify adj electrical adj test and @pd>"20050726"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/12/07 18:26
L24	1	((fail adj bit adj map) (wafer adj map) (wafer adj defect adj map)) and classify adj2 test and @pd>"20050726"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/12/07 18:26
L25	0	((fail adj bit adj map) (wafer adj map) (wafer adj defect adj map)) and analogous adj electrical adj test and @pd>"20050726"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/12/07 18:27
L26	0	((fail adj bit adj map) (wafer adj map) (wafer adj defect adj map)) and analogous adj electrical adj test and @pd>"20050726"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/12/07 18:27
L27	0	((fail adj bit adj map) (wafer adj map) (wafer adj defect adj map)) and (group grouping grouped categorize categorizing categorized) adj electrical adj test and @pd>"20050726"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/12/07 18:28
L28	1	((fail adj bit adj map) (wafer adj map) (wafer adj defect adj map)) and manufacturing adj records and @pd>"20050726"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/12/07 18:28
L29	4	((fail adj bit adj map) (wafer adj map) (wafer adj defect adj map)) and (manufactur\$3 with (history record)) and @pd>"20050726"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/12/07 18:28
L30	0	((fail adj bit adj map) (wafer adj map) (wafer adj defect adj map)) and fail adj density and @pd>"20050726"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/12/07 18:29
L31	1	((fail adj bit adj map) (wafer adj map) (wafer adj defect adj map)) and subarea and @pd>"20050726"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/12/07 18:35
L32	2	(wafer and test and map and (semiconductor chip) and (classif\$4 organiz\$3 group\$3) and calculat\$3 and failure).clm.	US-PGPUB	OR	ON	2005/12/07 18:37